



Product Change Notification - KSRA-11DUMC383

Date:

06 Feb 2020

Product Category:

32-bit Microcontrollers

Affected CPNs:**Notification subject:**

CCB 3553 Final Notice: Qualification of ASSH as an additional assembly site for selected CEC1702 device family available in 84L WFBGA (7x7x0.8mm) package.

Notification text:**PCN Status:**

Final notification.

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of ASSH as an additional assembly site for selected CEC1702 device family available in 84L WFBGA (7x7x0.8mm) package.

Pre Change:

Assembled at ANAC using HR-9004 die attach, G750E molding compound, HL832NXA substrate core and AUS320 solder mask material.

Post Change:

Assembled at ANAC using HR-9004 die attach, G750E molding compound, HL832NXA substrate core and AUS320 solder mask material or Assembled at ASSH using Film ATB-125 die attach, KE-G1250LKDS molding compound, CCL-HL832NX substrate core and AUS308 solder mask material.

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	Amkor Assembly & Test (Shanghai) Co., LTD (ANAC)	Amkor Assembly & Test (Shanghai) Co., LTD (ANAC)	ASE-Shanghai (ASSH)
Wire material	CuPdAu	CuPdAu	CuPdAu
Die attach material	HR-9004	HR-9004	Film ATB-125
Molding compound material	G750E	G750E	KE-G1250LKDS



Solder Ball Alloy	SAC105	SAC105	SAC105
Substrate material	HL832NXA	HL832NXA	CCL-H832NX
Solder mask	AUS320	AUS320	AUS308

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity and on-time delivery performance by qualifying ASSH as an additional assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

March 6, 2020 (date code: 2010)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	September 2018					-->	February 2020				March 2020				
	Workweek	36	37	37	39		40	6	7	8	9	10	11	12	13
Initial PCN Issue Date				X											
Qual Report Availability							X								
Final PCN Issue Date							X								
Estimated Implementation Date											X				

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

September 17, 2018: Issued initial notification.

February 6, 2020: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date to be on March 06, 2020.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.



Attachment(s):

[PCN_KSRA-11DUMC383_QUAL_REPORT.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

CEC1702Q-C1-SX

CEC1702Q-B1-SX

CEC1702Q-B1-SX-CN1

CEC1702Q-C2-I/SX

CEC1702Q-B2-I/SX

CEC1702Q-B2-I/SX-SM1

CEC1702Q-S1-I/SX

CEC1702Q-B1-SX-TR